Apparatus for mounting semiconductor chips

ABSTRACT

An apparatus for mounting semiconductor chips (12) comprises a pick and place system (4) with a bonding head (5), a picking head (7) and a support table (8). The picking head (7) and the support table (8) are mounted on a carriage (6). The apparatus can be operated in a direct mode and a parallel mode, wherein in the direct mode the carriage (6) is in the first position which is a parking position a control unit (9) operates the pick and place system (4) in such a way that the bonding head (5) removes one semiconductor chip (12) after the other from the wafer table (1) and places the same on the substrate (2). In the parallel mode, the carriage (6) is in the second position, and the control unit (9) operates the picking head (7), the support table (8) and the pick and place system (4) in such a way that the picking head (7) removes one semiconductor chip (12) after the other from the wafer table (1) and places the same on the support table (8), and the bonding head (5) removes one semiconductor chip (12) after the other from the support table (8) and places the same on the substrate (2).

(Fig. 1)